## MC74HC238A

## 1－of－8 Decoder／ Demultiplexer

## High－Performance Silicon－Gate CMOS

The MC74HC238A is identical in pinout to the LS238．The device inputs are compatible with standard CMOS outputs；with pullup resistors，they are compatible with LSTTL outputs．

The HC238A decodes a three－bit Address to one－of－eight active－high outputs．This device features three Chip Select inputs，two active－low and one active－high to facilitate the demultiplexing， cascading，and chip－selecting functions．The demultiplexing function is accomplished by using the Address inputs to select the desired device output；one of the Chip Selects is used as a data input while the other Chip Selects are held in their active states．

## Features

－Output Drive Capability： 10 LSTTL Loads
－Outputs Directly Interface to CMOS，NMOS and TTL
－Operating Voltage Range： 2.0 to 6.0 V
－Low Input Current： $1.0 \mu \mathrm{~A}$
－High Noise Immunity Characteristic of CMOS Devices
－In Compliance with the Requirements Defined by JEDEC Standard No．7A
－Chip Complexity： 100 FETs or 29 Equivalent Gates
－These are $\mathrm{Pb}-$ Free Devices＊
ON

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MARKING DIAGRAMS


| PDIP－16 <br> N SUFFIX <br> CASE 648 | 16 |
| :---: | :---: |
|  | 凸凸凸凸囚凸囚 |
|  | MC74HC238AN |
|  | O AWLYYWWG |
|  |  |

SOIC－16
D SUFFIX
CASE $751 B$

|  |
| :---: |
|  |  |
|  |  |
|  |  |

16

TSSOP－16 DT SUFFIX CASE 948F
A＝Assembly Location
WL，L＝Wafer Lot
YY，Y＝Year
WW，W＝Work Week
G or •＝Pb－Free Package
（Note：Microdot may be in either location）

ORDERING INFORMATION
See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet．
＊For additional information on our Pb－Free strategy and soldering details，please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual，SOLDERRM／D．

| A0 $\square^{\bullet}$ | 16 |
| :---: | :---: |
| A1 [ 2 | 15 |
| A2 3 | 14 |
| CS2 54 | 13 |
| CS3 [ 5 | 12 |
| CS1-6 | 11 |
| Y7 [7 | 10 |
| GND [ 8 | 9 |

Figure 1. Pin Assignment


Figure 2. Logic Diagram

ORDERING INFORMATION

| Device | Package | Shipping $^{\dagger}$ |
| :--- | :---: | :---: |
| MC74HC238ANG | PDIP-16 <br> (Pb-Free) | 500 Units / Rail |
| MC74HC238ADG | SOIC-16 <br> (Pb-Free) | 48 Units / Rail |
| MC74HC238ADR2G | SOIC-16 <br> (Pb-Free) | 2500 Tape \& Reel |
| MC74HC238ADTR2G | TSSOP-16* | 2500 Tape \& Reel |

$\dagger$ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb -Free.

TRUTH TABLE

| Inputs |  |  |  |  |  | Outputs |  |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| CS1 | CS2 | CS3 | A0 | A1 | A2 | Yo | Y1 | Y2 | Y3 | Y4 | Y5 | Y6 | Y7 |
| H | X | X | X | X | X | L | L | L | L | L | L | L | L |
| X | H | X | X | X | X | L | L | L | L | L | L | L | L |
| X | X | L | X | X | X | L | L | L | L | L | L | L | L |
| L | L | H | L | L | L | H | L | L | L | L | L | L | L |
| L | L | H | H | L | L | L | H | L | L | L | L | L | L |
| L | L | H | L | H | L | L | L | H | L | L | L | L | L |
| L | L | H | H | H | L | L | L | L | H | L | L | L | L |
| L | L | H | L | L | H | L | L | L | L | H | L | L | L |
| L | L | H | H | L | H | L | L | L | L | L | H | L | L |
| L | L | H | L | H | H | L | L | L | L | L | L | H | L |
| L | L | H | H | H | H | L | L | L | L | L | L | L | H |

## MC74HC238A

MAXIMUM RATINGS

| Symbol | Parameter | Value | Unit |
| :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{CC}}$ | DC Supply Voltage (Referenced to GND) | -0.5 to +7.0 | V |
| $V_{\text {in }}$ | DC Input Voltage (Referenced to GND) | -0.5 to $\mathrm{V}_{C C}+0.5$ | V |
| $\mathrm{V}_{\text {out }}$ | DC Output Voltage (Referenced to GND) | -0.5 to $\mathrm{V}_{C C}+0.5$ | V |
| $1{ }_{\text {in }}$ | DC Input Current, per Pin | $\pm 20$ | mA |
| $\mathrm{I}_{\text {out }}$ | DC Output Current, per Pin | $\pm 25$ | mA |
| $\mathrm{I}_{\mathrm{CC}}$ | DC Supply Current, $\mathrm{V}_{\mathrm{CC}}$ and GND Pins | $\pm 50$ | mA |
| $\mathrm{P}_{\mathrm{D}}$ | Power Dissipation in Still Air, Plastic DIP $\dagger$ <br>  SOIC Package $\dagger$ <br>  TSSOP Package $\dagger$ | $\begin{aligned} & 750 \\ & 500 \\ & 450 \end{aligned}$ | mW |
| $\mathrm{T}_{\text {stg }}$ | Storage Temperature | -65 to + 150 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\mathrm{L}}$ | Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP, SOIC or TSSOP Package) | 260 | ${ }^{\circ} \mathrm{C}$ |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
$\dagger$ Derating - Plastic DIP: $-10 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ from $65^{\circ}$ to $125^{\circ} \mathrm{C}$
SOIC Package: $-7 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ from $65^{\circ}$ to $125^{\circ} \mathrm{C}$
TSSOP Package: - 6.1 $\mathrm{W} /{ }^{\circ} \mathrm{C}$ from $65^{\circ}$ to $125^{\circ} \mathrm{C}$

## RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit |
| :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{CC}}$ | DC Supply Voltage (Referenced to GND) | 2.0 | 6.0 | V |
| $\mathrm{V}_{\text {in }}, \mathrm{V}_{\text {out }}$ | DC Input Voltage, Output Voltage (Referenced to GND) | 0 | $\mathrm{V}_{\mathrm{CC}}$ | V |
| $\mathrm{T}_{\mathrm{A}}$ | Operating Temperature, All Package Types | -55 | + 125 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{tr}_{\mathrm{r}} \mathrm{t}_{\mathrm{f}}$ | Input Rise and Fall Time $\mathrm{V}_{\mathrm{CC}}=2.0 \mathrm{~V}$ <br> (Figure 2) $\mathrm{V}_{\mathrm{CC}}=4.5 \mathrm{~V}$ <br>  $\mathrm{~V}_{\mathrm{CC}}=6.0 \mathrm{~V}$ | $\begin{aligned} & 0 \\ & 0 \\ & 0 \end{aligned}$ | $\begin{gathered} \hline 1000 \\ 500 \\ 400 \end{gathered}$ | ns |

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

| Symbol | Parameter | Test Conditions | $\begin{gathered} \mathrm{v}_{\mathrm{cc}} \\ \mathbf{V} \end{gathered}$ | Guaranteed Limit |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | $-55^{\circ} \mathrm{C}$ to $25^{\circ} \mathrm{C}$ | $\leq \mathbf{8 5}^{\circ} \mathrm{C}$ | $\leq 125^{\circ} \mathrm{C}$ |  |
| $\mathrm{V}_{\mathrm{IH}}$ | Minimum High-Level Input Voltage | $\begin{aligned} & \mathrm{V}_{\text {out }}=0.1 \mathrm{~V} \text { or } \mathrm{V}_{\mathrm{CC}}-0.1 \mathrm{~V} \\ & \left.\right\|_{\text {lout }} \leq 20 \mu \mathrm{~A} \end{aligned}$ | $\begin{aligned} & \hline 2.0 \\ & 3.0 \\ & 4.5 \\ & 6.0 \end{aligned}$ | $\begin{gathered} 1.5 \\ 2.1 \\ 3.15 \\ 4.2 \end{gathered}$ | $\begin{gathered} 1.5 \\ 2.1 \\ 3.15 \\ 4.2 \end{gathered}$ | $\begin{gathered} 1.5 \\ 2.1 \\ 3.15 \\ 4.2 \end{gathered}$ | V |
| $\mathrm{V}_{\text {IL }}$ | Maximum Low-Level Input Voltage | $\begin{aligned} & \begin{array}{l} \mathrm{V}_{\text {out }}=0.1 \mathrm{~V} \text { or } \mathrm{V}_{\mathrm{CC}}-0.1 \mathrm{~V} \\ \mid \mathrm{l}_{\text {out }} \end{array} \leq 20 \mu \mathrm{~A} \end{aligned}$ | $\begin{aligned} & \hline 2.0 \\ & 3.0 \\ & 4.5 \\ & 6.0 \end{aligned}$ | $\begin{gathered} \hline 0.5 \\ 0.9 \\ 1.35 \\ 1.8 \end{gathered}$ | $\begin{gathered} \hline 0.5 \\ 0.9 \\ 1.35 \\ 1.8 \end{gathered}$ | $\begin{gathered} \hline 0.5 \\ 0.9 \\ 1.35 \\ 1.8 \end{gathered}$ | V |
| $\mathrm{V}_{\mathrm{OH}}$ | Minimum High-Level Output Voltage | $\begin{aligned} & \mathrm{V}_{\text {in }}=\mathrm{V}_{\mathrm{IH}} \text { or } \mathrm{V}_{\mathrm{IL}} \\ & \mid l_{\text {out }} \leq 20 \mu \mathrm{~A} \end{aligned}$ | 2.0 <br> 4.5 <br> 6.0 <br> 3.0 <br> 4.5 <br> 6.0 | 1.9 <br> 4.4 <br> 5.9 <br> 2.48 <br> 3.98 <br> 5.48 | $\begin{aligned} & \hline 1.9 \\ & 4.4 \\ & 5.9 \\ & \hline 2.34 \\ & 3.84 \\ & 5.34 \end{aligned}$ | 1.9 4.4 5.9 2.20 3.70 5.20 | V |


| $\mathrm{V}_{\mathrm{OL}}$ | Maximum Low-Level Output Voltage | $\begin{aligned} & \mathrm{V}_{\text {in }}=\mathrm{V}_{\mathrm{IH}} \text { or } \mathrm{V}_{\mathrm{IL}} \\ & \mid \mathrm{l}_{\text {out }} \leq 20 \mu \mathrm{~A} \end{aligned}$ | $\begin{aligned} & 2.0 \\ & 4.5 \\ & 6.0 \end{aligned}$ | $\begin{aligned} & 0.1 \\ & 0.1 \\ & 0.1 \end{aligned}$ | $\begin{aligned} & 0.1 \\ & 0.1 \\ & 0.1 \end{aligned}$ | $\begin{aligned} & 0.1 \\ & 0.1 \\ & 0.1 \end{aligned}$ | V |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | $\begin{aligned} \mathrm{V}_{\text {in }}=\mathrm{V}_{\mathrm{IH}} \text { or } \mathrm{V}_{\mathrm{IL}} \mid & l_{\text {out }} \end{aligned} \leq 2.4 \mathrm{~mA}, ~ \mid l_{\text {out }} \leq 4.0 \mathrm{~mA}$ | $\begin{aligned} & 3.0 \\ & 4.5 \\ & 6.0 \end{aligned}$ | $\begin{aligned} & 0.26 \\ & 0.26 \\ & 0.26 \end{aligned}$ | $\begin{aligned} & 0.33 \\ & 0.33 \\ & 0.33 \end{aligned}$ | $\begin{aligned} & 0.40 \\ & 0.40 \\ & 0.40 \end{aligned}$ |  |
| $\mathrm{l}_{\text {in }}$ | Maximum Input Leakage Current | $\mathrm{V}_{\text {in }}=\mathrm{V}_{\text {CC }}$ or GND | 6.0 | $\pm 0.1$ | $\pm 1.0$ | $\pm 1.0$ | $\mu \mathrm{A}$ |
| Icc | Maximum Quiescent Supply Current (per Package) | $\begin{aligned} & \mathrm{V}_{\text {in }}=\mathrm{V}_{\mathrm{CC}} \text { or GND } \\ & \mathrm{I}_{\text {out }}=0 \mu \mathrm{~A} \end{aligned}$ | 6.0 | 4 | 40 | 160 | $\mu \mathrm{A}$ |

AC ELECTRICAL CHARACTERISTICS ( $\mathrm{C}_{\mathrm{L}}=50 \mathrm{pF}$, $\left.\operatorname{Input} \mathrm{t}_{\mathrm{r}}=\mathrm{t}_{\mathrm{f}}=6.0 \mathrm{~ns}\right)$

| Symbol | Parameter | $\underset{\mathbf{V}}{\mathrm{v}_{\mathrm{cc}}}$ | Guaranteed Limit |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | $-55^{\circ} \mathrm{C}$ to $25^{\circ} \mathrm{C}$ | $\leq 85^{\circ} \mathrm{C}$ | $\leq 125^{\circ} \mathrm{C}$ |  |
| $\begin{aligned} & \hline \mathrm{t}_{\mathrm{PLH}}, \\ & \mathrm{t}_{\mathrm{PH}} \end{aligned}$ | Maximum Propagation Delay, Input A to Output $Y$ (Figures 3 and 6) | $\begin{aligned} & 2.0 \\ & 3.0 \\ & 4.5 \\ & 6.0 \end{aligned}$ | $\begin{aligned} & 135 \\ & 90 \\ & 27 \\ & 23 \end{aligned}$ | $\begin{gathered} \hline 170 \\ 125 \\ 34 \\ 29 \end{gathered}$ | $\begin{aligned} & 205 \\ & 165 \\ & 41 \\ & 35 \end{aligned}$ | ns |
| $\mathrm{t}_{\mathrm{pLH}},$ | Maximum Propagation Delay, CS1 to Output $Y$ <br> (Figures 4 and 6) | $\begin{aligned} & 2.0 \\ & 3.0 \\ & 4.5 \\ & 6.0 \end{aligned}$ | $\begin{aligned} & 110 \\ & 85 \\ & 22 \\ & 19 \end{aligned}$ | $\begin{aligned} & 140 \\ & 100 \\ & 28 \\ & 24 \end{aligned}$ | $\begin{gathered} 165 \\ 125 \\ 33 \\ 28 \end{gathered}$ | ns |
| $\begin{aligned} & \mathrm{t}_{\mathrm{PLH}}, \\ & \mathrm{t}_{\mathrm{PH}}, \end{aligned}$ | Maximum Propagation Delay, CS2 or CS3 to Output Y (Figures 5 and 6) | $\begin{aligned} & 2.0 \\ & 3.0 \\ & 4.5 \\ & 6.0 \end{aligned}$ | $\begin{aligned} & 120 \\ & 90 \\ & 24 \\ & 20 \end{aligned}$ | $\begin{gathered} 150 \\ 120 \\ 30 \\ 26 \end{gathered}$ | $\begin{aligned} & 180 \\ & 150 \\ & 36 \\ & 31 \end{aligned}$ | ns |
| $\begin{aligned} & \mathrm{t}_{\mathrm{TLH}}, \\ & \mathrm{t}_{\mathrm{TH}}, \end{aligned}$ | Maximum Output Transition Time, Any Output (Figures 4 and 6) | $\begin{aligned} & 2.0 \\ & 3.0 \\ & 4.5 \\ & 6.0 \end{aligned}$ | $\begin{aligned} & 75 \\ & 30 \\ & 15 \\ & 13 \end{aligned}$ | $\begin{aligned} & 95 \\ & 40 \\ & 19 \\ & 16 \end{aligned}$ | $\begin{aligned} & 110 \\ & 55 \\ & 22 \\ & 19 \end{aligned}$ | ns |
| $\mathrm{C}_{\text {in }}$ | Maximum Input Capacitance | - | 10 | 10 | 10 | pF |


|  |  | Typical @ $\mathbf{2 5}{ }^{\circ} \mathbf{C}, \mathbf{\mathbf { V } _ { \mathbf { C C } } = \mathbf { 5 . 0 } \mathbf { V }}$ |  |
| :--- | :--- | :---: | :---: |
| $\mathrm{C}_{\mathrm{PD}}$ | Power Dissipation Capacitance (Per Package)* | 55 | pF |

[^0]
## SWITCHING WAVEFORMS



Figure 3.


Figure 4.

*Includes all probe and jig capacitance
Figure 6. Test Circuit

## PIN DESCRIPTIONS

## ADDRESS INPUTS

## A0, A1, A2 (Pins 1, 2, 3)

Address inputs. These inputs, when the chip is selected, determine which of the eight outputs is active-low.

## CONTROL INPUTS

## CS1, CS2, CS3 (Pins 6, 4, 5)

Chip select inputs. For CS1 at a high level and CS2, CS3 at a low level, the chip is selected and the outputs follow the

Address inputs. For any other combination of CS1, CS2, and CS3, the outputs are at a logic high.

## OUTPUTS

Y0 - Y7 (Pins 15, 14, 13, 12, 11, 10, 9, 7)
Active-high Decoded outputs. These outputs assume a high level when addressed and the chip is selected. These outputs remain low when not addressed or the chip is not selected.

EXPANDED LOGIC DIAGRAM


## PACKAGE DIMENSIONS

PDIP-16
N SUFFIX
CASE 648-08
ISSUE T


SOIC-16
D SUFFIX
CASE 751B-05
ISSUE J


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANS Y14.5M, 1982.
CONTROLLING DIMENSION: MILLIMETER.
DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION
2. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
3. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION

|  | MILLIMETERS |  |  | INCHES |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
| DIM | MIN | MAX | MIN | MAX |  |
| A | 9.80 | 10.00 | 0.386 | 0.393 |  |
| B | 3.80 | 4.00 | 0.150 | 0.157 |  |
| C | 1.35 | 1.75 | 0.054 | 0.068 |  |
| D | 0.35 | 0.49 | 0.014 | 0.019 |  |
| F | 0.40 | 1.25 | 0.016 | 0.049 |  |
| G | 1.27 | BSC | 0.050 | BSC |  |
| J | 0.19 | 0.25 | 0.008 | 0.009 |  |
| K | 0.10 | 0.25 | 0.004 | 0.009 |  |
| M | $0^{\circ}$ | $7^{\circ}$ | $00^{\circ}$ | $7^{\circ}$ |  |
| P | 5.80 | 6.20 | 0.229 | 0.244 |  |
| R | 0.25 | 0.50 | 0.010 | 0.019 |  |

## PACKAGE DIMENSIONS

TSSOP-16
DT SUFFIX
CASE 948F-01
ISSUE A


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[^0]:    *Used to determine the no-load dynamic power consumption: $P_{D}=C_{P D} V_{C C}{ }^{2 f}+I_{C C} V_{C C}$.

